

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Faraday Technology Marketing Group, LLC	05/29/2008

RECEIVING PARTY DATA

Name:	Faraday Technology, Inc.
Street Address:	315 Huls Drive
City:	Clayton
State/Country:	OHIO
Postal Code:	45315

PROPERTY NUMBERS Total: 17

Property Type	Number
Patent Number:	6750144
Patent Number:	7022216
Patent Number:	6827833
Patent Number:	6203684
Patent Number:	6303014
Patent Number:	6319384
Patent Number:	6878259
Patent Number:	6524461
Patent Number:	6210555
Patent Number:	6309528
Patent Number:	6863793
Patent Number:	6652727
Patent Number:	6402931
Patent Number:	6551485
Patent Number:	6558231

PATENT

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REEL: 021006 FRAME: 0905

OP \$680.00 6750144

Patent Number:	6221235
Patent Number:	6676825

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:

461987-00001

NAME OF SUBMITTER:

Mark P. Levy

Total Attachments: 5

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PATENT ASSIGNMENT

The undersigned, Faraday Technology Marketing Group, LLC, an Ohio limited liability company as the owner of the issued patents and pending patent applications identified in Schedule A ("Assignor") for good and valuable consideration, receipt of which is hereby acknowledged, does hereby sell, assign and transfer to Faraday Technology, Inc., an Ohio corporation ("Assignee"), its successors and assigns, the entire right, title and interest for the United States of America and its territorial possessions, and all foreign countries including all rights of priority, in the patents and patent applications identified in Schedule A, and all inventions or improvements therein, and in and to all Letters Patent of the United States and all foreign countries which may or shall be granted on said inventions, or any parts thereof, or any divisional, continuing, reissue or other applications based in whole or in part thereon, such rights to be held and enjoyed by Assignee as fully and entirely as the same would have been held and enjoyed by Assignor had this assignment not been made, including without limitation the right to sue and recover damages for past infringement.

Assignor agrees to execute all applications, amended specifications, deeds or other instruments, and to do all acts necessary or proper to secure the grant of Letters Patent in the United States and in all other countries to Assignee, to vest and confirm in said corporation, its successors and assigns, the legal title to all such patents.

[SIGNATURE PAGE TO FOLLOW]

IN WITNESS WHEREOF, the Assignor hereto has executed this Agreement as of the date below.

FARADAY TECHNOLOGY MARKETING GROUP, LLC.

By:
Title:

Earl Jennings Taylor

Stephen Brunner
Witness

State of Ohio
) SS:
County of Montgomery

I, Julie K. Waggoner, do hereby certify that Earl Jennings Taylor this day appeared before me personally and did acknowledge that he did execute and deliver the foregoing instrument by signing his name, for the purposes therein named and expressed.

In Witness Whereof, I set my hand and official seal this 29th day of May, 2008.

Julie K. Waggoner
Notary Public

Commission expires:

JULIE K. WAGGONER, Notary Public
In and for the State of Ohio
My Commission Expires April 3, 2009

SCHEDULE A
ISSUED PATENTS

Owner	Title	Country	Patent No.	Issue Date
Faraday Technology Marketing Group, LLC	Method for Electrochemical Metallization and Planarization of Semiconductor Substrates Having Features of Different Sizes	United States	6750144	6/15/2004
Faraday Technology Marketing Group, LLC	Electrolytic Removal of Excess Metal Plating	United States	7022216	4/4/2006
Faraday Technology Marketing Group, LLC	Electrodeposition of Metals in High-Aspect Ratio Cavities Using Modulated Reverse Electric Fields	United States	6827833	12/7/2004
Faraday Technology Marketing Group, LLC	Pulse Reverse Electrodeposition for Metallization and Planarization of a Semiconductor Substrates	United States	6203684	3/20/2001
Faraday Technology Marketing Group, LLC	Pulse Reverse Electrodeposition for Metallization and Planarization of a Semiconductor Substrates	United States	6303014	10/16/2001
Faraday Technology Marketing Group, LLC	Pulse Reverse Electrodeposition for Metallization and Planarization of a Semiconductor Substrates	United States	6319384	11/20/2001
Faraday Technology Marketing Group, LLC	Pulse Reverse Electrodeposition for Metallization and Planarization of a Semiconductor Substrates	United States	6878259	4/12/2005
Faraday Technology Marketing Group, LLC	Pulse Reverse Electrodeposition for Metallization and Planarization of a Semiconductor Substrates	United States	6524461	2/25/2003
Faraday Technology Marketing Group, LLC	Electrodeposition of Metals in Small Recesses for Manufacture of High Density Interconnects Using Reverse Pulse Plating	United States	6210555	4/3/2001
Faraday Technology Marketing Group, LLC	Electrochemical Metallization for Multiple Feature Sizes	United States	6309528	10/30/2001
Faraday Technology Marketing Group, LLC	Electrochemical Metallization for Multiple Feature Sizes	United States	6863793	3/8/2005
Faraday Technology Marketing Group, LLC	Electrochemical Metallization for Multiple Feature Sizes	United States	6652727	11/25/2003
Faraday Technology Marketing Group, LLC	Electrochemical Machining Using Modulated Reverse Electric Fields	United States	6402931	6/11/2002

Faraday Technology Marketing Group, LLC	Electrodeposition of Metals for Forming Three-Dimensional Microstructures	United States	6551485	4/22/2003
Faraday Technology Marketing Group, LLC	Sequential Electromachining and Electropolishing of Metals and the Like Using Modulated Electric Fields	United States	6558231	5/6/2003
Faraday Technology Marketing Group, LLC	Removal of Sacrificial Cores by Electrochemical Machining	United States	6221235	4/24/2001
Faraday Technology Marketing Group, LLC	Removal of Sacrificial Cores by Electrochemical Machining	United States	6676825	1/13/2004
Faraday Technology Marketing Group, LLC	Pulse Reverse Electrodeposition for Metallization and Planarization of a Semiconductor Substrates	Mexico	228426	6/10/2005

PENDING PATENT APPLICATIONS

Owner	Title	Country	Application No.	Filing Date
Faraday Technology Marketing Group, LLC	Pulse Reverse Electrodeposition for Metallization and Planarization of a Semiconductor Substrates	Patent Cooperation Treaty	US99/23653 continuation of 09/239,811, continuation of 09/172,299	10/14/1999
Faraday Technology Marketing Group, LLC	Electrodeposition of Catalytic Metals Using Pulsed Electric Fields	Patent Cooperation Treaty	US99/25611 continuation of 09/184,247	11/2/1999
Faraday Technology Marketing Group, LLC	Removal of Sacrificial Cores By Electrochemical Machining	Patent Cooperation Treaty	US99/28176 continuation of 09/200,959	11/30/1999
Faraday Technology Marketing Group, LLC	Electrochemical Etching of Circuitry for High Density Interconnect Electronic Modules	Patent Cooperation Treaty	US2007/061738 continuation of 11/354,376	2/7/2007
Faraday Technology Marketing Group, LLC	Tin and Alloy Electroplating Method with Controlled Internal Stress and Grain Size of the Resulting Deposit	Patent Cooperation Treaty	US2007/060027 claims priority from prov. appl. 60/756,634	1/3/2007
Faraday Technology Marketing Group, LLC	Electrolytic Looping for Forming Layering in the Deposit of a Coating	Patent Cooperation Treaty	US2007/074063 continuation of 11/501,551	7/23/2007